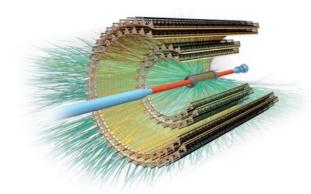


LXV International Conference on Nuclear Physics «Nucleus 2015. New Horizons in Nuclear Physics, Nuclear Engineering, Femto- and Nanotechnologies»



June 29 – July 3, 2015, Saint-Petersburg

# The new Inner Tracking System of the ALICE experiment: physics, design and performance





V. Manzari
INFN and CERN





on behalf of the ALICE Collaboration

# **Outline**



# **ALICE Today**

ALICE Upgrade Strategy

Inner Tracking System Upgrade

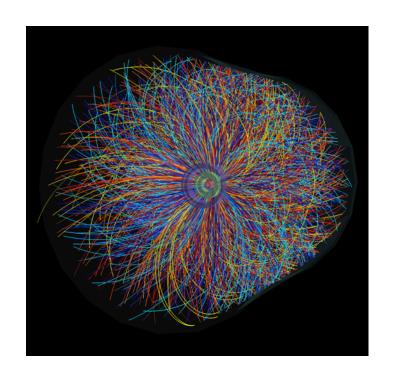
Design Objectives

Layout and Components

Performance

Timeline

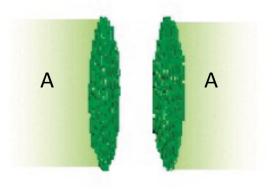
Conclusions



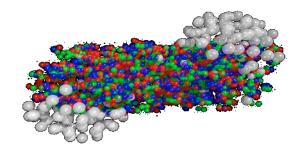
# **Study of QGP properties**



ALICE is the CERN LHC experiment designed to study the physics of strongly interacting matter at extreme conditions of energy density (~15 GeV/fm³) and temperature over a large volume (~ 1000 fm³), and in particular the properties of the Quark Gluon Plasma (QGP), using

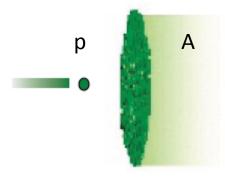


nucleus-nucleus collisions (A-A)



pp 'baseline', for the needed normalization

$$R_{AA}(,p_{T}) = \frac{1}{N_{coll}} \times \frac{dN_{AA}/dp_{T}}{dN_{pp}/dp_{T}}$$



proton-nucleus (p-A) to discriminate between initial state effects and final state effects Cronin effect modified PDF in nuclei

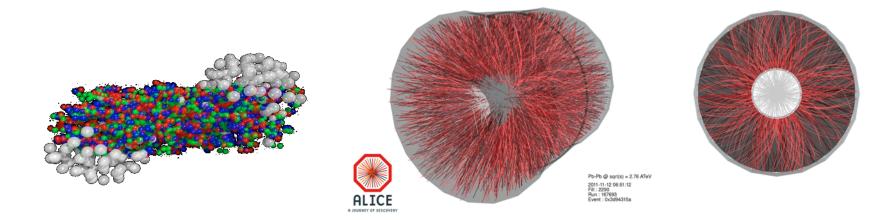
energy loss in the medium hadronization mechanisms (fragmentation vs coalescence)

# **Study of QGP properties**



Prior to LHC HI programme, nature of QGP – "a nearly perfect liquid" – emerged from experiments at CERN SPS and BNL RHIC

**ALICE** confirms basic picture: observation of hot hadronic matter at unprecedented values of temperatures, densities and volumes ....

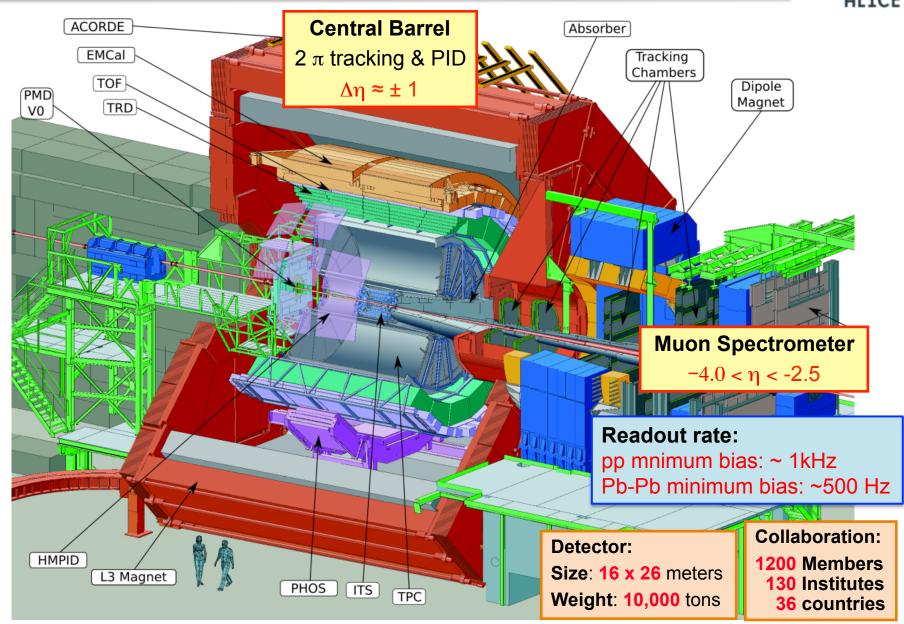


... and exceeding the precision and kinematic reach of all significant probes of the QGP measured in the past decades

→ Excellent capabilities to measure high-energy nuclear collisions at LHC

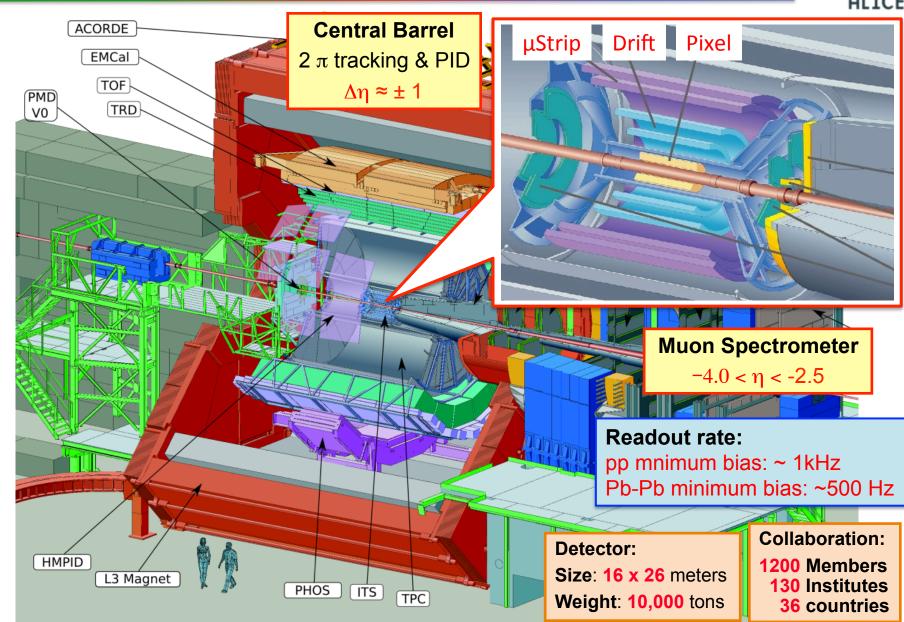
### The current ALICE Detector





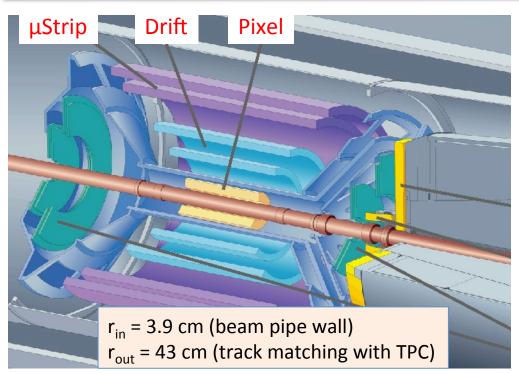
### The current ALICE Detector

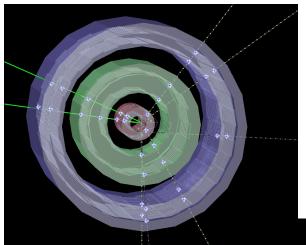




# The current Inner Tracking System







6 concentric barrels of silicon detectors based on 3 different technologies

- 2 layers of Silicon Pixel (SPD), material  $X/X_0$  1.14 % /layer  $\rightarrow$  tracking and MB trigger
- 2 layers of Silicon Drift (SDD) → tracking and particle identification
- 2 layers of double-sided Silicon  $\mu$ Strips (SSD)  $\rightarrow$  tracking and particle identification

### **ITS Tasks**



Prompt Level-0 trigger capability with a maximum latency of < 800 ns (Pixel)

Improve primary vertex reconstruction, momentum and impact parameter resolution

Standalone tracking and PID of low  $p_T$  particles

Reconstruction of secondary vertices from c and b decays with high resolution

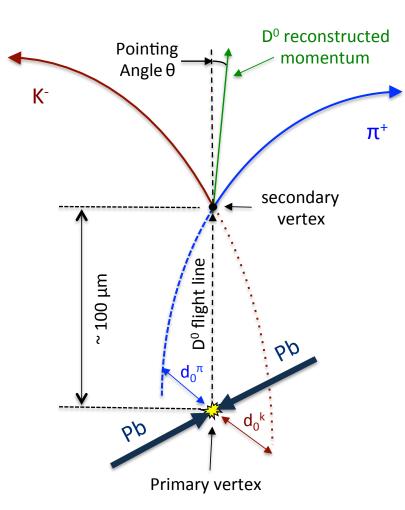
Measurement of charged particles pseudo-rapidity distribution

Event pile-up rejection

# ITS Upgrade – Secondary Vertex Determination



### Example: D<sup>0</sup> meson



### Open charm

| Particle                              | Decay Channel   | <b>c</b> τ (μ <b>m</b> ) |
|---------------------------------------|-----------------|--------------------------|
| D <sup>0</sup>                        | K- π+ (3.8%)    | 123                      |
| D <sup>+</sup>                        | K-π+π+ (9.5%)   | 312                      |
| <b>D</b> <sub>s</sub> ⁺               | K+ K- π+ (5.2%) | 150                      |
| $\Lambda_{c}^{\scriptscriptstyle{+}}$ | p K-π+ (5.0%)   | 60                       |

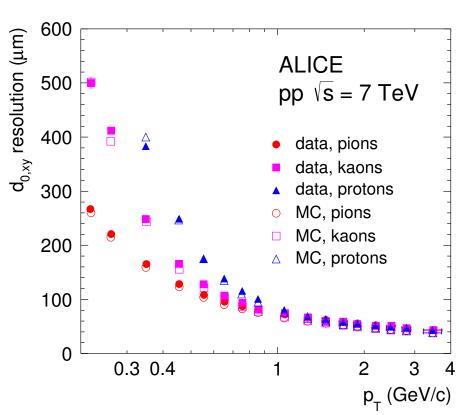
Analysis based on decay topology and invariant mass technique

How precisely is d<sub>0</sub> measured with the current ITS detector?

# **Current ITS – Impact Parameter Resolution**

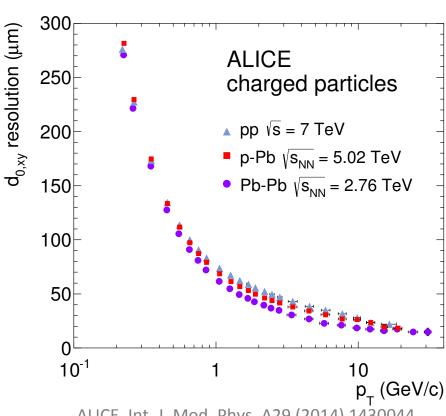


### Very good MC description



ALICE, Int. J. Mod. Phys. A29 (2014) 1430044

### Very weak dependence on the colliding system



ALICE, Int. J. Mod. Phys. A29 (2014) 1430044

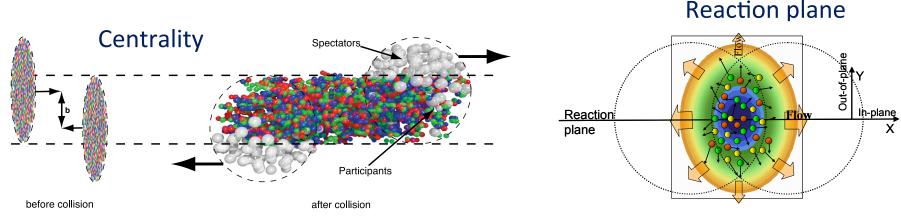
 $\sim$ 70 µm at p<sub>T</sub> = 1 GeV/c

# **ALICE Upgrade: Detailed Characterization of QGP**



### Progress on the characterization of QGP properties

- precision measurements of rare probes
- over a large kinematic range: from high to very low transverse momenta
- as function of multi-differential observables: centrality, reaction plane, ...



Upgrade physics plans focus on physics observables where ALICE detector unique features are essential

PID, low material thickness, precise vertexing and tracking down to low p<sub>t</sub>

### **Example:**

precision measurements of spectra, correlations and flow of heavy flavour hadrons and quarkonia at low transverse momenta (not possible to trigger!)

# **ALICE Upgrade Strategy**



➤ The ALICE Upgrade Physics Programme requires

**statistics** (luminosity)

Target for Run3+4: Pb-Pb recorded luminosity  $\geq 10 \text{ nb}^{-1} \Rightarrow 8 \times 10^{10} \text{ evts}$ 

### precision measurements

### I. Upgrade detectors, readout systems and online systems

- o read out all Pb-Pb interactions at a maximum rate of **50kHz** (i.e. L=6x10<sup>27</sup> cm<sup>-2</sup>s<sup>-1</sup>), with a minimum bias trigger (at present 500Hz)
  - → Gain a factor 100 in statistics wrt originally approved programme (Run1+2)

# II. Significant improvement of vertexing and tracking capabilities at low p<sub>T</sub>

**New Inner tracking System** 

It targets LHC 2<sup>nd</sup> Long Shutdown (2019/20)



ALICE Upgrade Lol September 2012

> Addendum September 2013



# **ITS Upgrade Design Features**

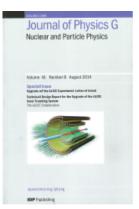
- 1. Improve impact parameter resolution by a factor of ~3
- Get closer to IP (position of first layer): 39mm →23mm
- Reduce x/X<sub>0</sub> /layer: ~1.14% → ~ 0.3% (for inner layers)
- Reduce pixel size: 50μm x 425μm → O(30μm x 30μm)
- 2. Improve tracking efficiency and  $p_T$  resolution at low  $p_T$
- Increase granularity:
  - 6 layers → 7 layers
  - silicon drift and strips pixels
- 3. Fast readout

J. Phys. G (41) 087002

- readout Pb-Pb interactions at > 100 kHz and pp interactions at  $\sim$  several 10<sup>5</sup> Hz (currently limited at 1kHz with full ITS)
- 4. Fast insertion/removal for yearly maintenance
- possibility to replace non functioning detector modules during yearly shutdown



CERN-LHCC-2013-24



# **Memorandum of Understanding**





### Project approval process completed

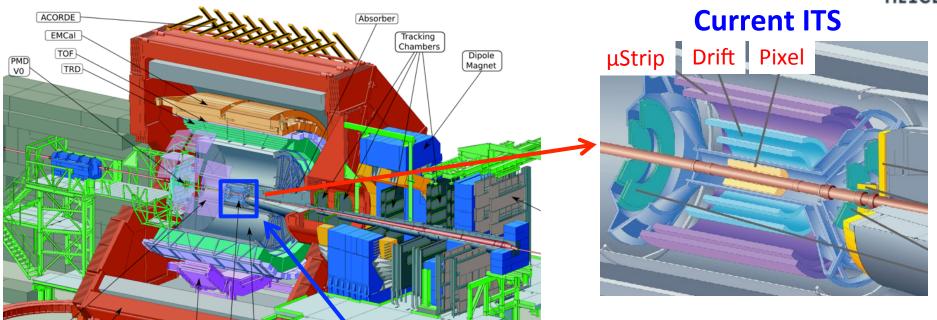
- Conceptual Design Report Dec 2012
- Technical Design Report Dec 2013
- Upgrade Cost Group Review Mar 2014
- Research Board Approval Mar 2014

### Responsibilities & Funding (ITS Upgrade MoU)

Signed Apr 2015

# **ALICE New ITS**





# **ITS Upgrade Objectives**

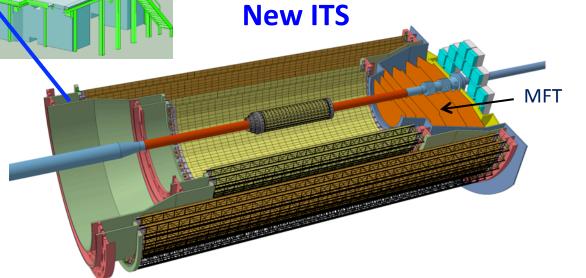
HMPID

Increase readout rate: > x 50

PHOS ITS

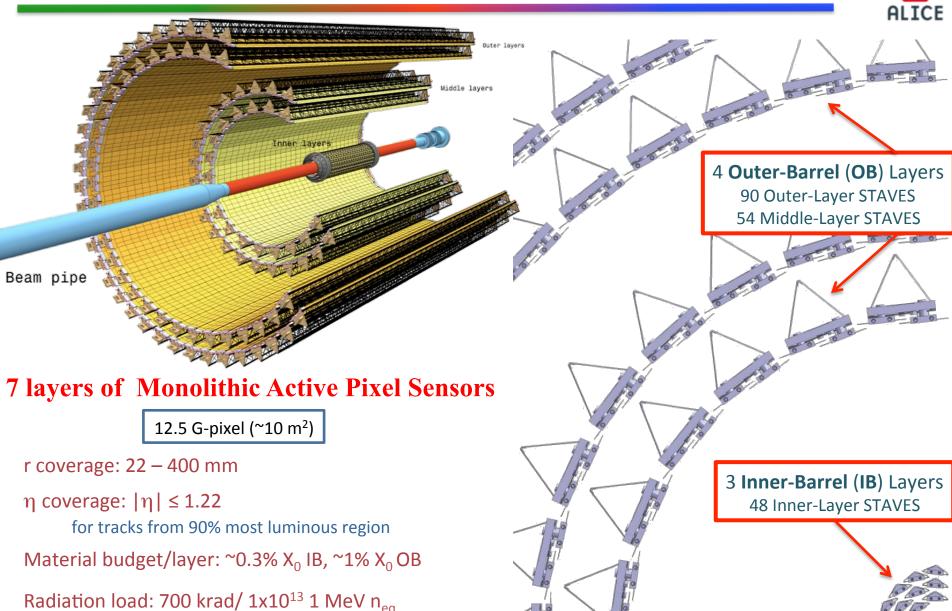
TPC

 Increase vertexing and tracking accuracy



### The New ITS

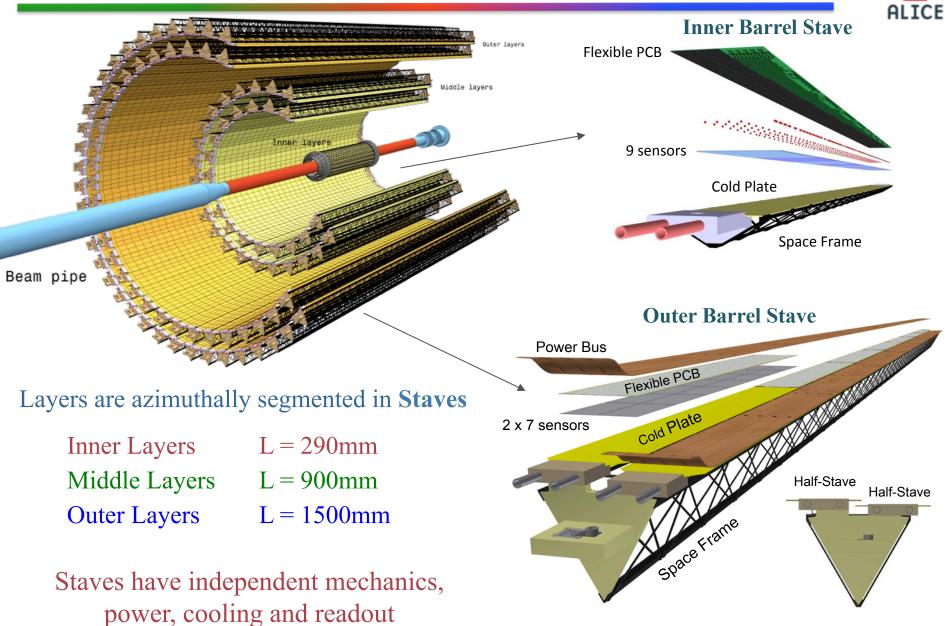




includes safety factor 10

### **New ITS Staves**

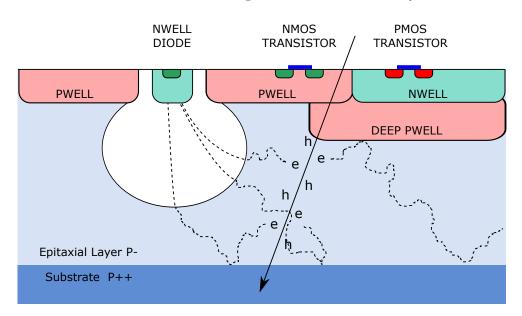




# **Pixel Chip – Technology choice**



### CMOS Pixel Sensor using TowerJazz 0.18µm CMOS Imaging Process

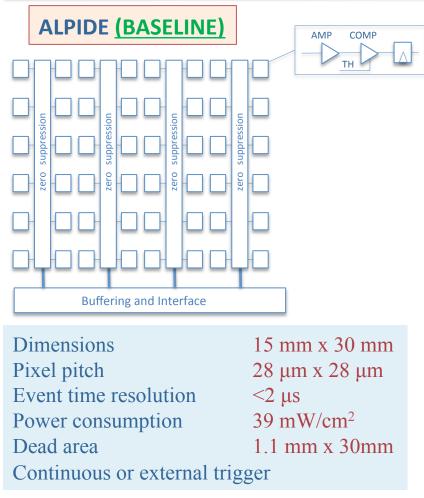


### Tower Jazz 0.18 μm CMOS

- feature size 180 nm
- metal layers 6
- → Suited for high-density, low-power
- Gate oxide 3nm
- → Circuit rad-tolerant
- High-resistivity (>  $1k\Omega$  cm) p-type epitaxial layer ( $20\mu$ m  $40\mu$ m thick) on p-type substrate
- > Small n-well diode (2-3 μm diameter), ~100 times smaller than pixel => low capacitance
- ► Application of (moderate) reverse bias voltage to substrate can be used to increase depletion zone around NWELL collection diode
- Quadruple well process: deep PWELL shields NWELL of PMOS transistors, allowing for full CMOS circuitry within active area

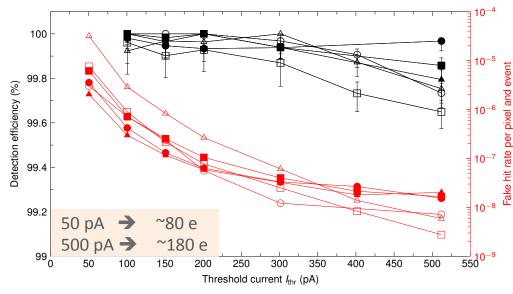
# **Pixel Chip**





### Efficiency and fake hit rate

- Measurements at CERN PS: 5-7 GeV  $\pi^-$  Dec '14
- $50 \mu m$  thick chips: 3 non irradiated and 3 irradiated with neutrons at  $10^{13} 1 MeV n_{eq} / cm^2$



 $\lambda_{\text{fake}} < < 10^{-5} / \text{ event/pixel @ } \epsilon_{\text{det}} > 99\%$ 

→ large margin over design requirements

### Back-up architecture **MISTRAL-O**:

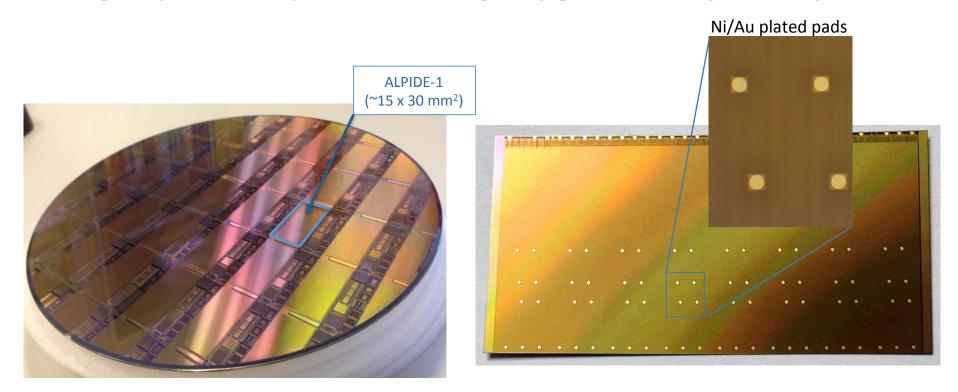
identical dimensions, physical and electrical interfaces

for more details see Poster of V.I. Zherebchevsky et al.

# **Interconnection of pixel chip to Flex PCB (FPC)**



- Solder Contact Pads are distributed over the matrix (custom designed)
- Wafer post-processing:
  - chip Al pads need to be covered with Ni-Au (wet-able surface) in order to solder the chip on the Flexible Printed Circuit (FPC)
  - plating is done using electroless Ni-Au plating, prior to thinning and dicing

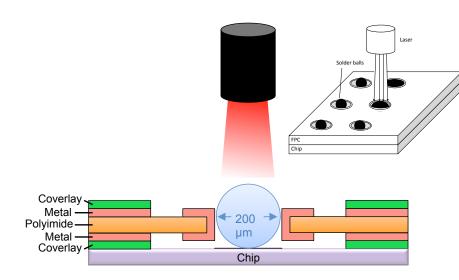


# Interconnection of pixel chip to Flex PCB (FPC)

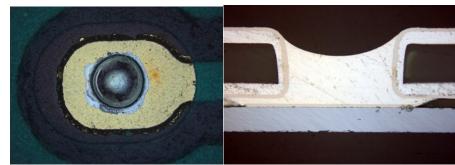


# **Laser Soldering**

- Flux-less soldering of 200 µm diameter Sn/Ag(96.5/3.5) balls (227 °C melting T) in vacuum (≤10<sup>-1</sup> mbar)
- IR diode laser, 976 nm, 25 W, 50 mm focal length, 250 mm beam spot size
- Laser power modulated by pyrometer, programmable T profile ensures precise limitation of heating
- Soldering mask (in Macor® or Rubalit ®) used to press FPC on chip and guide soldering balls inside FPC vias
- Solder provides electrical and mechanical connection → no glue

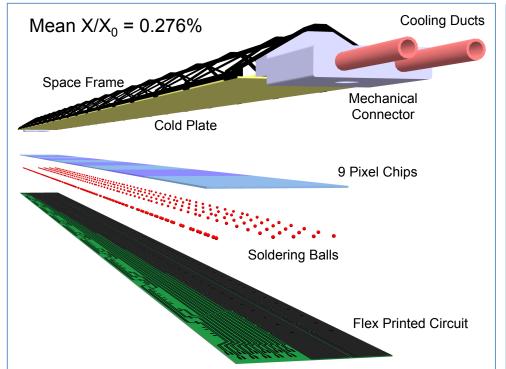


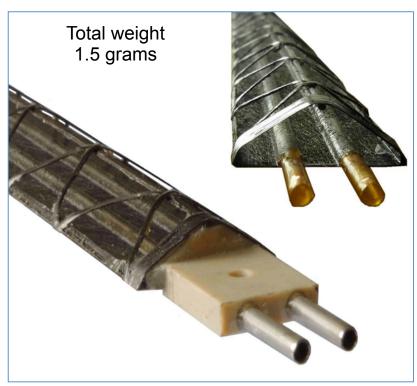




### **Inner Barrel Stave**







<Radius> (mm): 23, 31, 39

Nr. of staves: 12, 16, 20

Nr. of chips/layer: 108, 144, 180

Power density: < 100 mW/cm<sup>2</sup>

Length in z (mm): 290

Nr. of chips/stave: 9

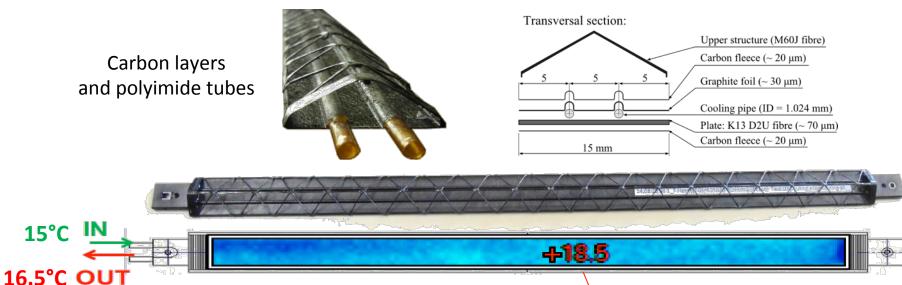
Material thickness: ~ 0.3% X<sub>0</sub>

Throughput (@100kHz):  $< 80 \text{ Mb/s} \times \text{cm}^{-2}$ 

### **Inner Barrel Stave**



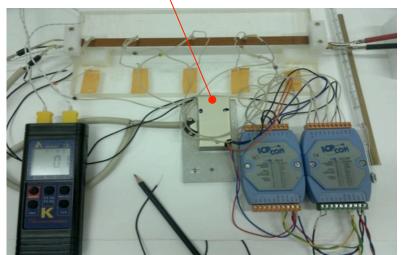
- ✓ New innovative stave design developed for the ALICE ITS Upgrade
- ✓ Thermal characterization of the inner barrel stave at St Petersburg University



0.15 W cm<sup>-2</sup>, 3.0 L h<sup>-1</sup>

Water cooling leakless system

Temperature non-uniformity < 5°C



# **Inner Barrel – Full-scale Prototype**

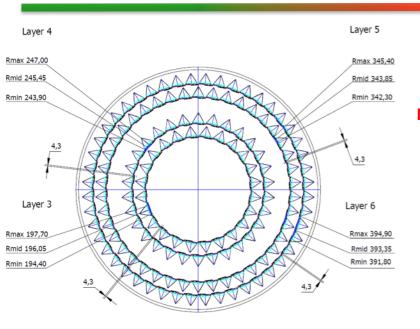


Cold Plate & Spaceframe carbon structure ~ 290mm, 1.5gr



### **Outer Barrel Stave**





### Outer Barrel (OB): 2 ML + 2 OL

Radial position (mm): 196, 245, 344, 393

Length in z (mm): 843, 1475

Nr. of staves: 24, 30, 42, 48

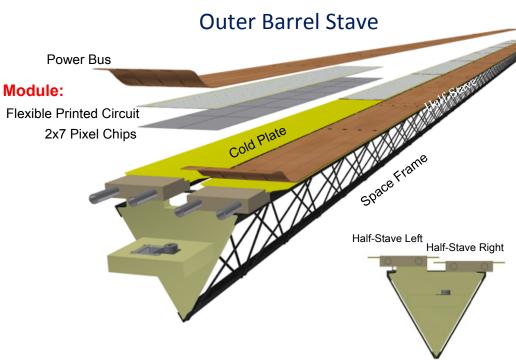
Nr. of half-staves/stave: 2

Nr. of modules/half-stave: 4 (ML), 7 (OL)

Nr. of chips/module: 14

Nr. of chips/layer: 2688, 3360, 8232, 9408

Material thickness:  $\sim 1\% X_0$  per layer



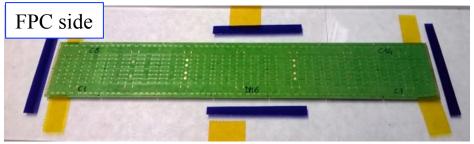
# Module to Module and Power Bus connections

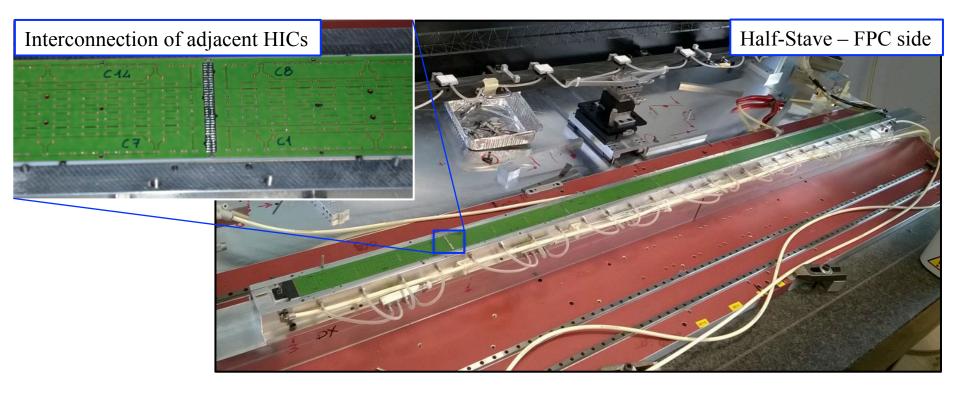


# **Outer Barrel – Full-Scale Module and Stave Prototypes**



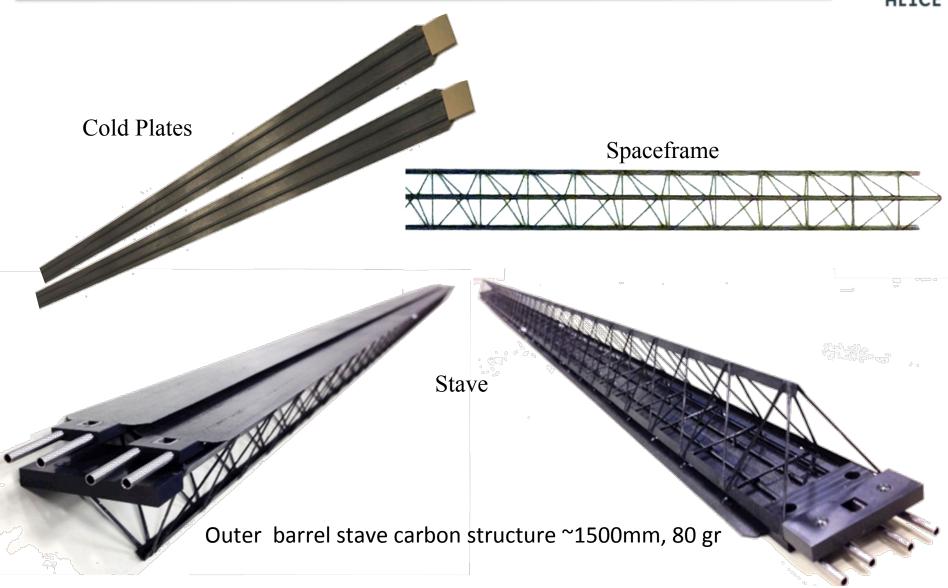






# **Outer Barrel Stave – Full-scale Prototype**





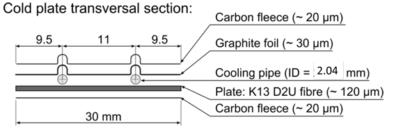
### **Outer Barrel – Cold Plate**

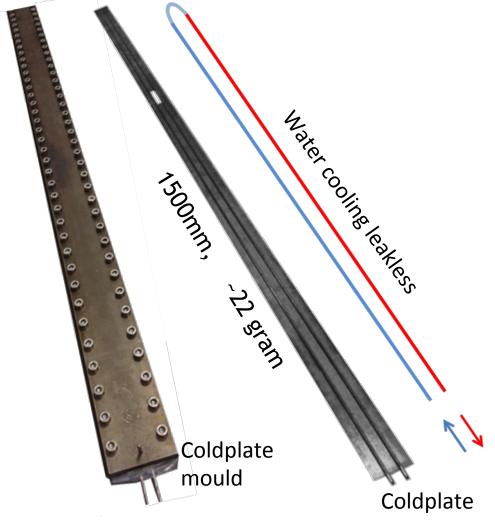


- ✓ New innovative cold plate design developed for the ALICE ITS Upgrade
- ✓ A new mould for cold plate manufacturing being produced at St Petersburg Univ.



### Carbon layers and polyimide tubes

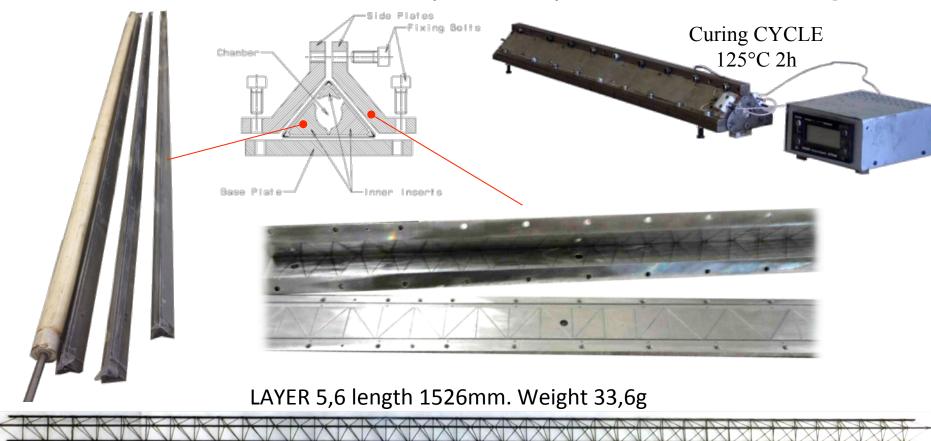




# **Outer Barrel – Spaceframe**



- ✓ A 1.5m spaceframe is required for the ALICE ITS Upgrade
- ✓ A new mould to manufacture such spaceframe produced at St Petersburg Univ.

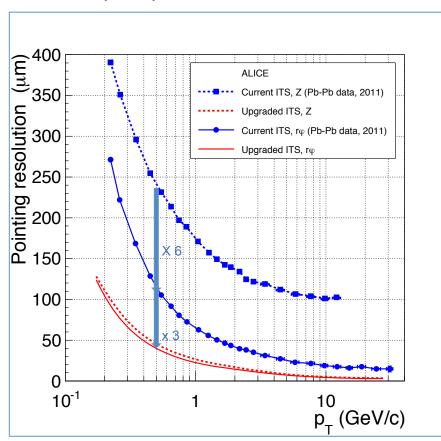


LAYER3,4 length 900mm. Weight 18g

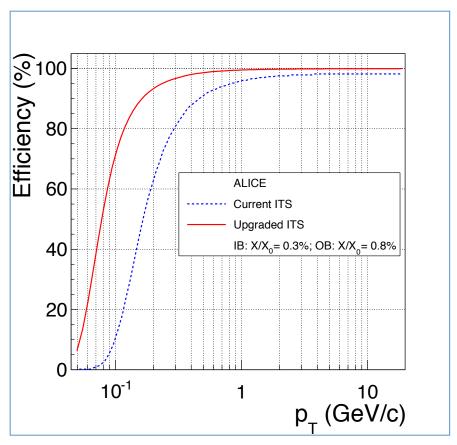
# **Performance of new ITS**



### Impact parameter resolution



### Tracking efficiency (ITS standalone)

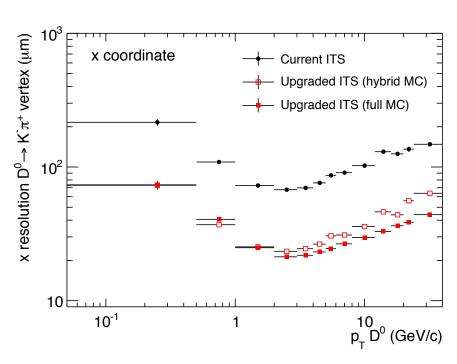


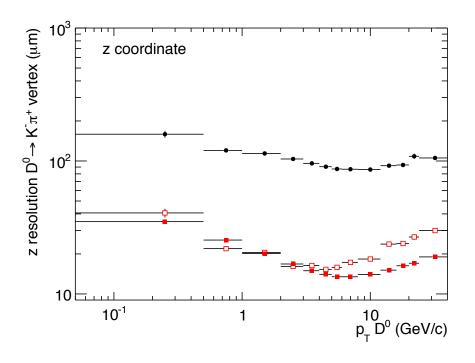
 $^{\sim}40 \ \mu m \ at \ p_{T} = 500 \ MeV/c$ 

## **Performance of new ITS**



# $D^0 \rightarrow K^-p^+$ secondary vertex position resolution

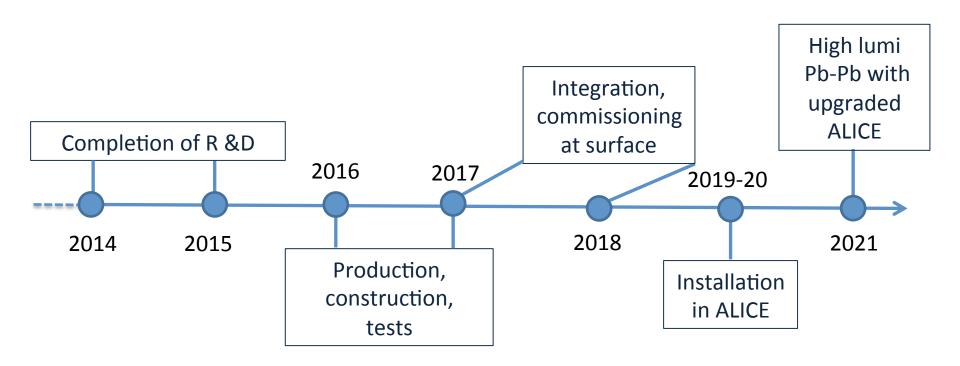




J. Phys. G (41) 087002

# **Project Timeline**





### **Conclusions**



ALICE has excellent capabilities to measure high-energy nuclear collisions at LHC

The ALICE Upgrade will allow a detailed characterization of the QGP

The new ITS will enhance the ALICE capabilities to measure heavy-flavour hadrons and quarkonia

The ITS Upgrade project has been fully approved and is well on-track for the installation during LS2 (2019-2020)

### **ALICE ITS Collaboration**

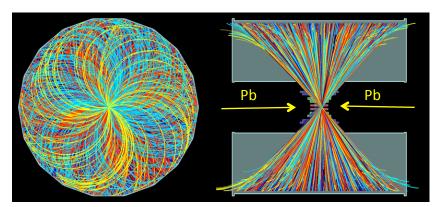
CERN, China (Wuhan), Check Republic (Prague), France (Grenoble, Strasbourg),
Italy (Aless., Bari, Cagliari, Catania, Frascati, Padova, Roma, Trieste, Torino),
Indonesia (LIPI), Korea (Pusan, Inha, Yonsei), Netherlands (Nikhef, Utrecht),
Pakistan (CIIT-Islamabad), Russia (St. Petersburg), Slovakia (Kosice),
Thailand (Suranaree, SLRI, TMEC), UK (Daresbury, Liverpool, RAL), Ukraine (Kharkov),
USA (Austin, Berkeley)



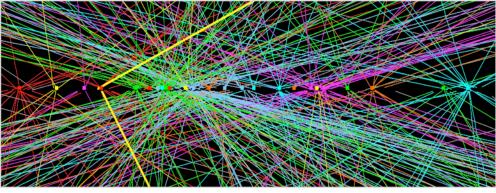
# Why Silicon Pixel Detector in HEP Experiments



Silicon Pixel Detectors are high granularity detectors, which provide unambiguous and precise hit information in a harsh environment close to the interaction point



LHC Pb-Pb collision (ALICE, Sep 2011)



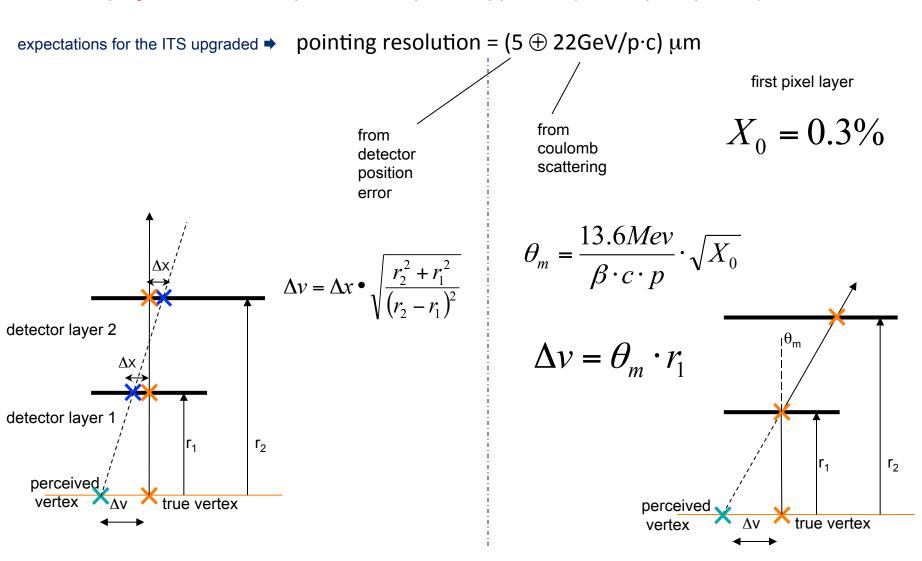
**LHC pp collisions**: a candidate Z boson event in the dimuon decay with 25 reconstructed vertices. (ATLAS, April 2012)

- Position resolution down to few microns
- Unambiguous hit information in high track density region
- High resolution for determination primary and secondary vertex
- Fast readout
- High level of radiation hardness

# What determines the Impact Parameter Resolution



Vertex projection from two points: a simplified approach (telescope equation)

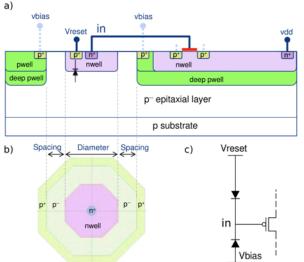


## **pALPIDE-1** – Main Design Features



#### ALPIDE Full Scale prototype

- Dimensions: 30mm x 15 mm
- Pixel Matrix: 1024 cols x 512 rows
- Pixel pitch: 28μm x 28μm
- Peaking time (defines time res): <2μs</li>
- Pulse length: 10-20μs
- In-pixel discriminator + 1 register
- Power consumption: < 40mW/cm<sup>2</sup>
- 4 sectors with different pixels



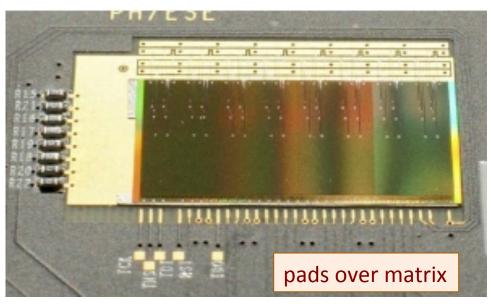


Figure: picture of pALPIDE-1

| Sector | nwell<br>diameter | spacing | pwell<br>opening | reset |
|--------|-------------------|---------|------------------|-------|
| 0      | 2μm               | 1μm     | 4μm              | PMOS  |
| 1      | 2μm               | 2μm     | 6μm              | PMOS  |
| 2      | 2μm               | 2μm     | 6μm              | Diode |
| 3      | 2μm               | 4μm     | 10μm             | PMOS  |

## **ALICE Upgrade Strategy**



- The upgrade plans entails building
  - New, high-resolution, high-rate ITS
  - Upgrade of TPC with replacement of MWPCs with
     GEMs and new pipelined readout electronics
  - Upgrade of readout electronics of: TRD, TOF, PHOS and Muon Spectrometer
  - Upgrade of the forward trigger detectors and ZDC
  - Upgrade of the online systems (DAQ & HLT)
  - Upgrade of the offline reconstruction framework
  - New 5-plane silicon telescope in front of the hadron absorber covering the acceptance of the muon Spectrometer
- It targets 2018/19 (LHC 2<sup>nd</sup> Long Shutdown)



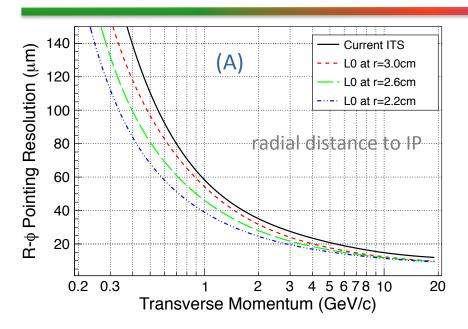
Lol Sep 2012

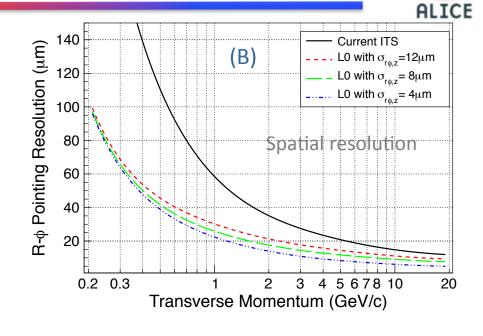


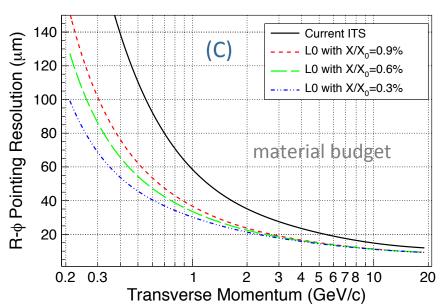
02

Add. Lol Sep 2013

## ITS Upgrade: Impact Parameter studies







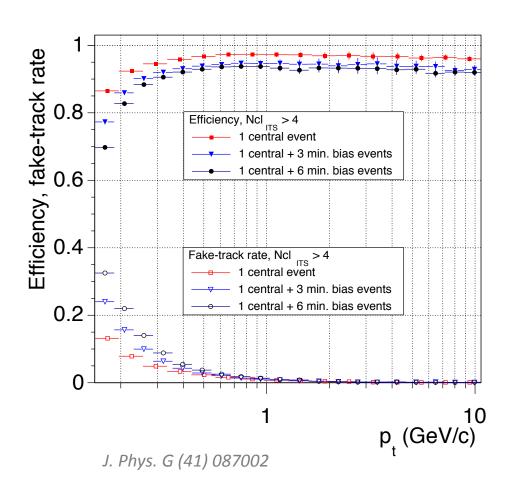
- Current ALICE ITS
  - ♦ radial position of first layer: 39mm
  - $\Rightarrow$  x/X<sub>0</sub>: 1.14% per layer
  - spatial resolution (r-phi): 12 μm
- A) current ITS + L0: x/X0 = 0.3%, res.=4 $\mu$ m;
- B) current ITS + L0: r = 22mm,  $x/X_0 = 0.3\%$ ;
- C) current ITS + L0: r = 22mm,  $x/X_0 = 0.3\%$ ;

ALICE ITS Upgrade CDR, CERN-LHCC-2012-12

## **Performance of ITS Upgrade**



Matching efficiency between the tracks reconstructed in the upgraded ITS and TPC for different values of event pile-up



The average event pile-up depends on the interaction rate and detector integration time

interaction rate 50 kHz integration time: 4 – 30 μs

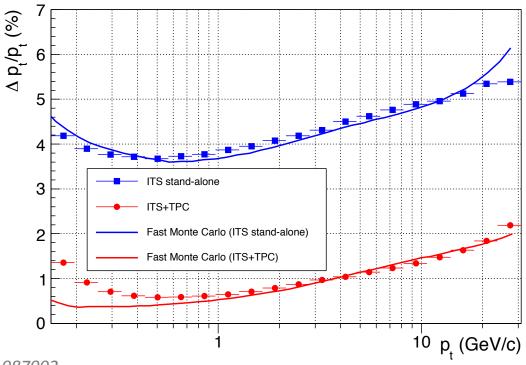
For 30 µs integration time (worst case design):

<pile-up> = 1 central + 1.5 min. bias

## **Performance of ITS Upgrade**



#### MOMENTUM RESOLUTION



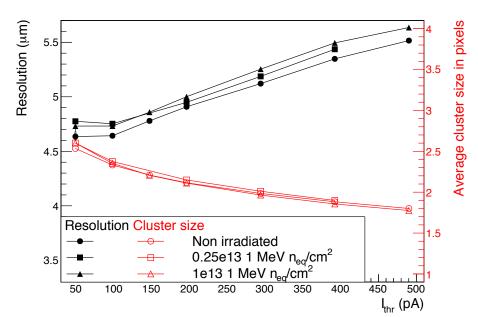
J. Phys. G (41) 087002

Transverse momentum resolution as function of  $p_T$  for primary charged pions for the upgraded ITS and current ITS. The results are shown for ITS standalone and ITS-TPC combined tracking.

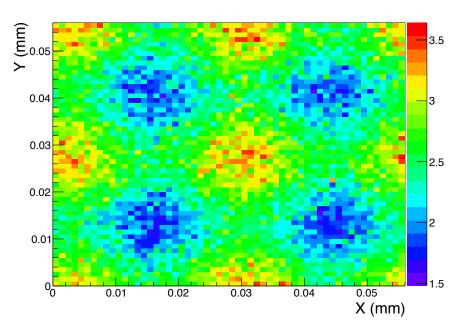
## pALPIDE-1 – Test Beam results at PS (9/14)



#### Spatial resolution



#### Cluster size vs. position within pixel



#### $\sigma_{\text{det}}$ < 5 $\mu m$ is achieved with sufficient margin of operation

- Measurements at PS: 5-7 GeV  $\pi^-$  September 2014
- Results refer to 50  $\mu m$  thick chips: non irradiated and irradiated with neutrons 0.25 x  $10^{13}$  and  $~10^{13}$  1MeV  $n_{eq}$  /  $cm^2$

## **Pixel Chip Requirements**

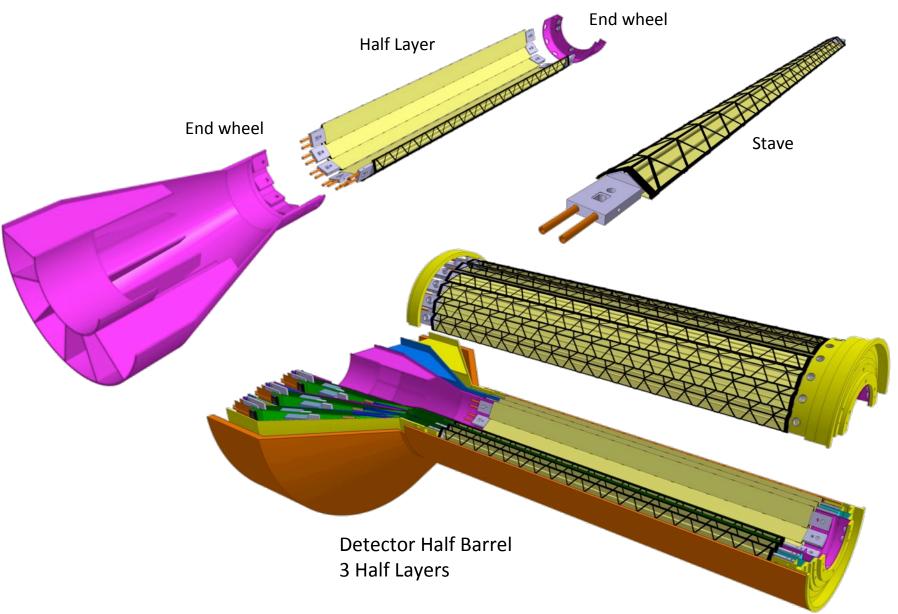


| Parameter                   | Inner Barrel   | Outer Barrel  |  |
|-----------------------------|--|---|--|
| Silicon thickness           | 50 μm  |   |  |
| Spatial resolution          | 5 μm   | <b>10</b> μm  |  |
| chip dimensions             | 15 mm x 30 mm  |   |  |
| Power density               | < 300 mW/cm <sup>2</sup>                                   | < 100 mW/cm <sup>2</sup>                                |  |
| Event time resolution       | < 30 μs  |   |  |
| Detection efficiency        | > 99%  |   |  |
| Fake hit rate               | < 10 <sup>-5</sup> per readout frame                       |   |  |
| TID radiation hardness (*)  | 2700 krad  | 100 krad  |  |
| NIEL radiation hardness (*) | 1.7x10 <sup>13</sup> 1MeV n <sub>eq</sub> /cm <sup>2</sup> | 10 <sup>12</sup> 1MeV n <sub>eq</sub> / cm <sup>2</sup> |  |

 $<sup>^{(*)}</sup>$  10 x radiation load integrated over approved programme (~ 6 years of operation)

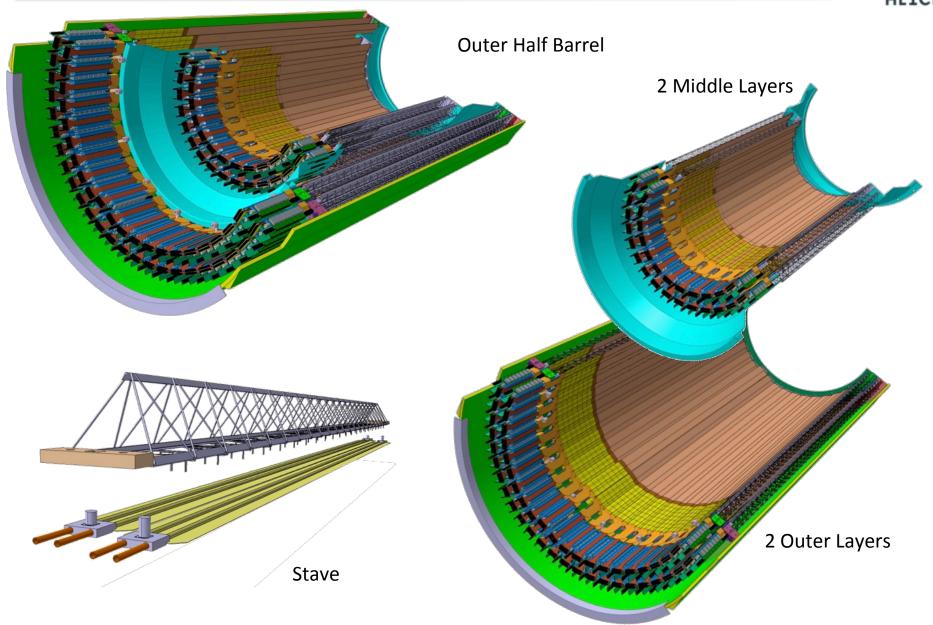
## **Inner Barrel**

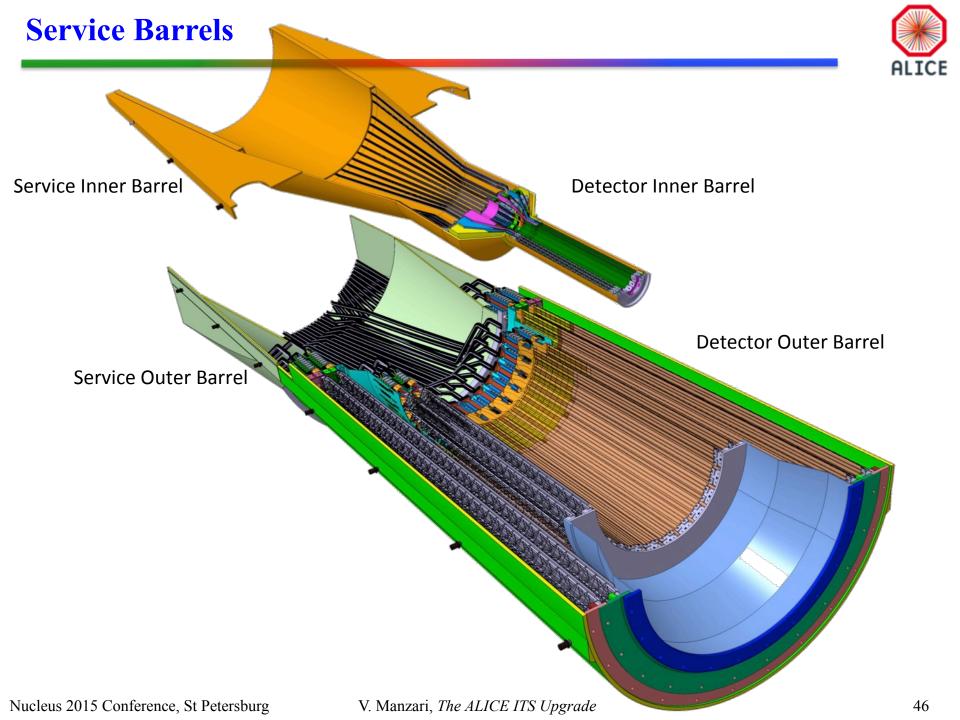




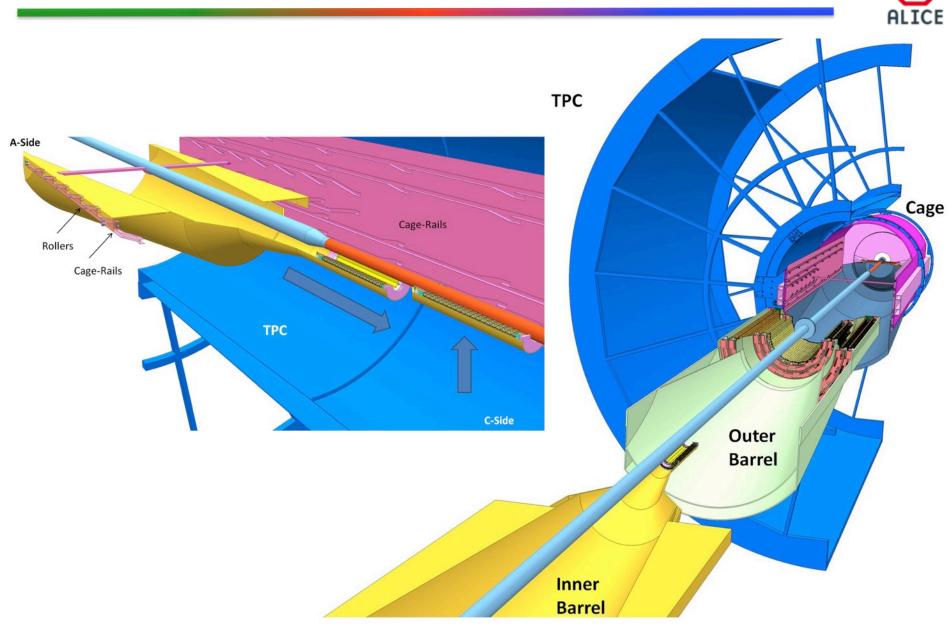
## **Outer Barrel**

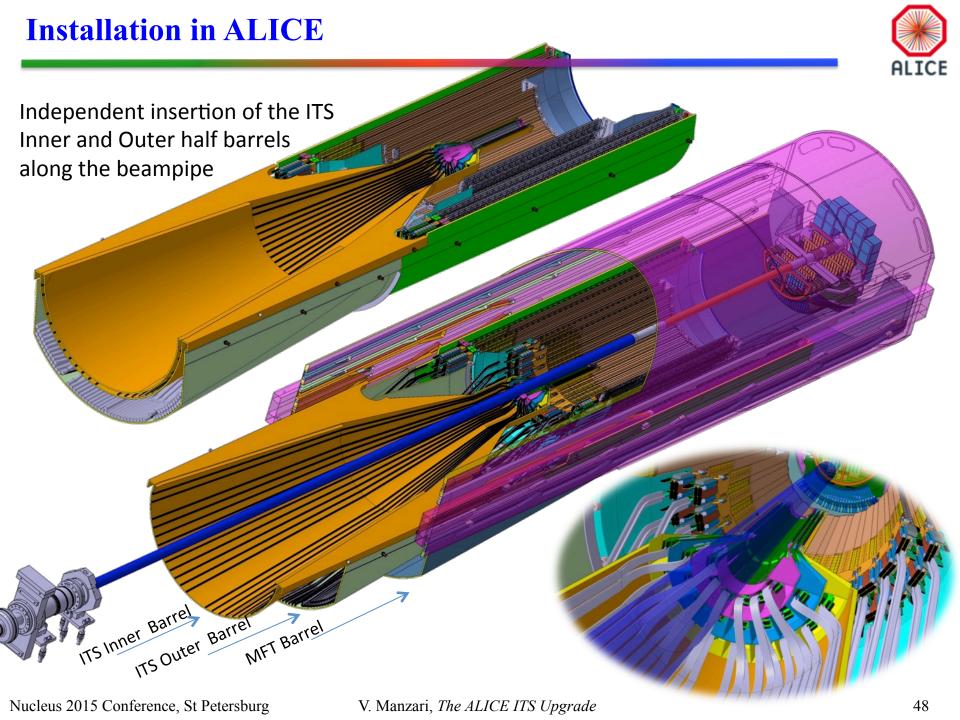






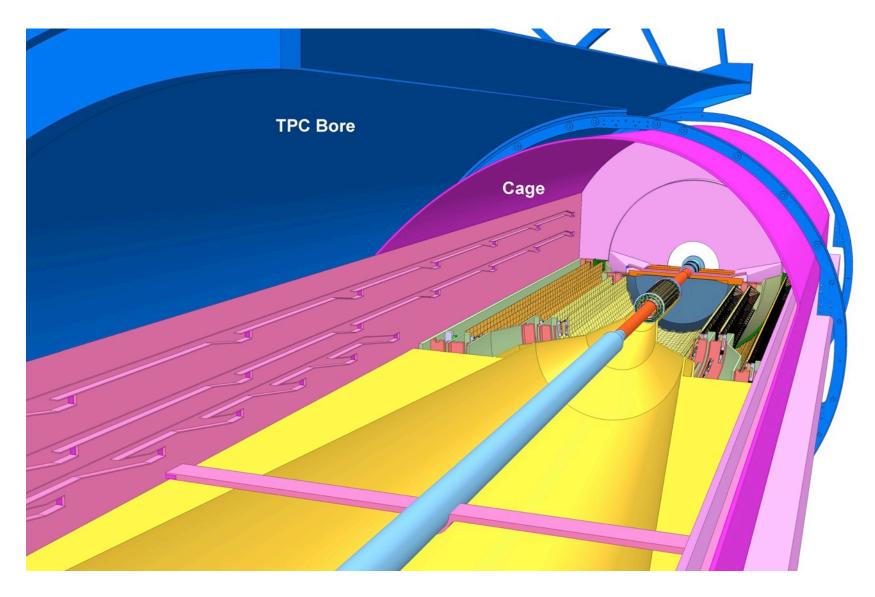
# **Installation in ALICE**



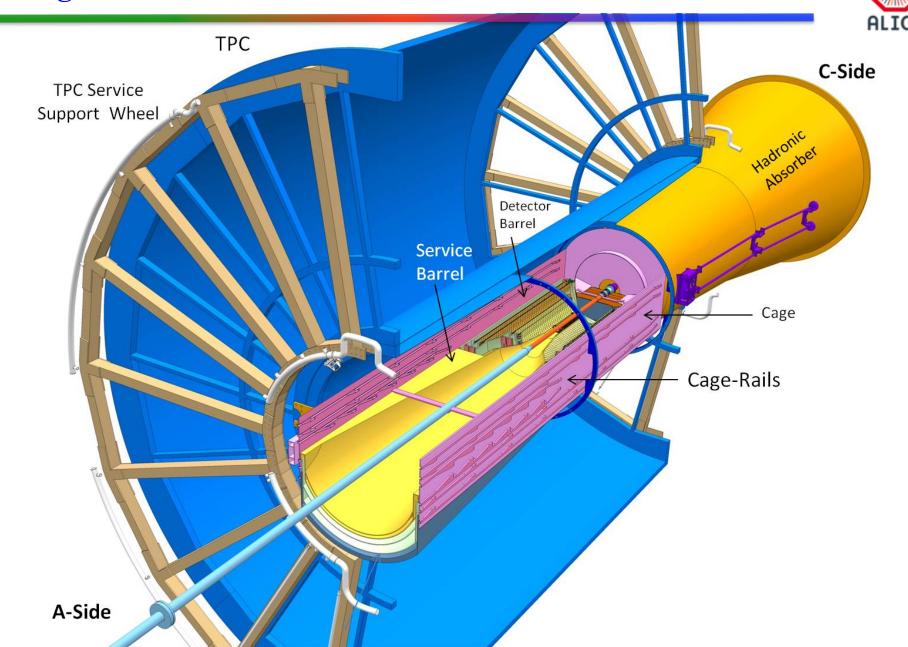


## **Integration in ALICE**





## **Integration in ALICE**



## **ALICE Approved Programme**



#### **RUN1 (2010 - 2013)**

| Year | System | Energy sqrt(s <sub>NN</sub> ) | Integrated lumin        |
|------|--------|-------------------------------|-------------------------|
| 2010 | Pb-Pb  | 2.76 TeV                      | ~ 0.01 nb <sup>-1</sup> |
| 2011 | Pb-Pb  | 2.76 TeV                      | ~ 0.1 nb <sup>-1</sup>  |
| 2013 | p-Pb   | 5.02 TeV                      | ~ 30 nb <sup>-1</sup>   |

### **RUN2 (2015 - 2018)**

• 1nb<sup>-1</sup> for Pb-Pb collisions, with improved detectors and double energy